

Amendments to the Claims

Claim 1 (**Previously Presented**) A wafer handling checker comprising:

a plurality of training operation wafers each formed of a semiconductor or ceramics to which a conductive film is applied on a face thereof, or a material having conductive properties;

a cassette having a plurality of slots for housing the plurality of training operation wafers, and a plurality of electrodes for contacting the plurality of training operation wafers when the plurality of training operation wafers are inserted into the plurality of slots;

a vacuum pincette having a conductive suction part for operating on the plurality of training operation wafers;

voltage application means for applying a voltage between each electrode of the cassette and the conductive suction part of the vacuum pincette; and

state detection means for detecting contact between the vacuum pincette and each training operation wafer by detecting a potential of each electrode of the cassette or a current flowing to an electrode.

Claim 2 (**Previously Presented**) The wafer handling checker according to Claim 1, wherein the cassette has display means for specifying a training operation wafer to be operated on based on operation specification information.

Claim 3 (**Previously Presented**) The wafer handling checker according to Claim 2, further comprising decision means for deciding whether an erroneous operation occurs based on a result of detection by the state detection means and the operation specification information.

Claim 4 (**Previously Presented**) The wafer handling checker according to Claim 3, wherein the decision means has output means for generating sound when the decision means decides the erroneous operation has occurred.

Claim 5 (**New**) A wafer handling checker comprising:

a plurality of training operation wafers each formed of a semiconductor or ceramics to which a conductive film is applied on a face thereof, or a material having conductive properties;

a cassette having a plurality of slots for housing the plurality of training operation wafers, and a plurality of electrodes for contacting the plurality of training operation wafers when the plurality of training operation wafers are inserted into the plurality of slots;

a vacuum pincette having a conductive suction part for operating on the plurality of training operation wafers; and

a controller operable to apply a voltage between each electrode of the cassette and the conductive suction part of the vacuum pincette, and detect contact between the vacuum pincette and each training operation wafer by detecting a potential of each electrode of the cassette or a current flowing to an electrode.

Claim 6 **(New)** The wafer handling checker according to Claim 5, wherein the cassette has a display operable to specify a training operation wafer to be operated on based on operation specification information.

Claim 7 **(New)** The wafer handling checker according to Claim 6, wherein the controller is further operable to decide whether an erroneous operation occurs based on a result of detection and the operation specification information.

Claim 8 **(New)** The wafer handling checker according to Claim 7, wherein the controller is further operable to cause a sound to be generated when the erroneous operation has occurred.